

## REMARKS

The only outstanding rejections of claims 11-22 are based solely on the assertion that the previously pending claims improperly recaptured subject matter surrendered during the prosecution of the aren't application. Although these assertions are respectfully traversed, the accompanying amendments are offered in an effort to eliminate any further concerns that the office may have regarding the recapture issue.

### **Independent Claim 1 of the original patent**

Claim 1 in the original application incorporated the limitation of "a first bus bar which is electrically isolated from said die attach platform and said plurality of leads."

In the amendment dated July 8, 1999, claim 1 was amended to:

- (1) Add the language relating to the attachment pads – the specific language added read **"each of sad elongated leads including a circular portion formed as an attachment pad."**
- (2) Add the paragraph (b).

### **Claim 11 of the pending reissue application**

In the foregoing amendments, claim 11 has been amended to positively recite the fact that the contacts include attachment pads (a feature added to claim 1 in the amendment dated July 8, 1999) but more broadly defines the attachment pads by not requiring any specific geometry. More specifically, the relevant clause reads:

a lead frame including a die attach platform, a plurality of contacts that are spaced apart from the die attach platform and a bus bar that is positioned between the die attach platform and at least some of the contacts, wherein bottom surfaces of the die attach platform, the contacts and the bus bar are substantially co-planar, **and wherein each of the contacts includes a portion that forms an attachment pad;**

With this language, claim 11 as presently presented is narrower than the claim 1 of the original patent application was before claim 1 was amended with respect to the attachment pad feature that was added during prosecution of original claim 1. As such the original claim scope has not been recaptured. MPEP 1412.02 (I)(C)(2)(d) discusses the application of the “recapture” rule to claims that broader than the issued claims, but narrower in relevant part than the cancelled claims in the original application. It is respectfully submitted that claim 11 falls squarely within the permissible type of broadening reissue claims discussed in MPEP 1412.02 (I)(C)(2)(d).

In view of the foregoing, it is respectfully submitted that claim 11, as currently pending does not improperly recapture subject matter surrendered in the application for the patent upon which the present reissue is based. Accordingly, it is respectfully submitted that the pending rejections of claim 11, and claims 12-18 that depend therefrom, should be withdrawn.

### **Independent Claim 19**

Claims 19-22 are directed towards modules that includes a package and a printed circuit board, wherein the package has a lead frame having a die attach platform and contacts that are substantially co-planar and exposed on the bottom surface of the package, with the die attach pad being used as a ground electrode. This claim is directed at a very different feature than the bus bars recited in the original independent claim 1 from the original application. Accordingly, it is believed that no amendments are required for this claim. However, if the Examiner believes it would help expedite prosecution of this case, we would be happy to add an explicitly recitation of the attachment pads to claim 19 as well.

**Independent Claim 23**

Independent Claim 23 has been added. This new claim also positively recites the attachment pads feature. Accordingly, it is respectfully submitted that this claim is also in proper condition for allowance.

Should the Examiner believe that a telephone conference would expedite the prosecution of this application, the undersigned can be reached at the telephone number set out below.

Respectfully submitted,  
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